

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MICRON.106C1APPLICATION NO.
10/027,519INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(USE SEVERAL SHEETS IF NECESSARY)

APPLICANT
Li et al.FILING DATE
December 20, 2001GROUP
Unknown

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
VU	5,807,607	9/15/98	Smith et al.			
VY	5,843,535	12/1/98	Dobson			
VY	5,874,367	2/23/99	Dobson			
VY	5,858,880	1/12/99	Dobson et al.			
VY	5,972,862	10/26/99	Torii et al.			
VY	6,008,540	12/28/99	Lu et al.			
VY	6,076,585	6/20/00	Klingbeil et al.			
VY	6,130,152	10/10/00	Smith et al.			
VY	6,140,245	10/31/00	Sharan			

COPY OF PAPERS
ORIGINALLY FILED

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
VY	Advanced SiO ₂ Planarization Using Silane and H ₂ O ₂ , Semiconductor International 86, December 1994, pp. 86-88.
VY	Techniques for Planarizing Device Topography, Kathy Skidmore, April 1988, pp. 115-119.
VY	Allied Signal Advanced Materials, Spin/Bake/Cure Procedure for Spin-On-Glass Materials for Interlevel and Internetal Dielectric Planarization, pp. 1-5.
VY	TechNotes, Advanced Electronics Resins, Dow Chemical Company, Process Guide for Photo-Imageable BCB, pp. 1-5.

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EXAMINER

J. Theivon

DATE CONSIDERED

11/07/03

*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.